

**Product / Package Information**

Package	LQFP_EP
Lead Count	100
Body Size	14 X 14 X 1.4 (6.0 EP)
Terminal Finish	100 Sn

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	4.03 E-01	86.91	869100	60.60		606016
Thermosets	Epoxy and Phenol resin	Proprietary	5.93 E-02	12.78	127800	8.91		89114
Other inorganic materials	Carbon black	1333-86-4	1.44 E-03	0.31	3100	0.22		2162
Subtotal			4.64 E-01	100	1000000	69.73		697292

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.38 E-01	97.5	975000	20.80		208022
Copper & its alloys	Iron	7439-89-6	3.33 E-03	2.35	23500	0.50		5014
Copper & its alloys	Zinc	7440-66-6	1.70 E-04	0.12	1200	0.03		256
Copper & its alloys	Phosphorus	7723-14-0	4.26 E-05	0.03	300	0.01		64
Subtotal			1.42 E-01	100.00	1000000	21.34		213356

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.10 E-03	100	1000000	0.17		1660

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	9.94 E-03	100	1000000	1.49		14949

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious Metals	Gold	7440-57-5	2.80 E-03	99	990000	0.42		4213
Precious Metals	Palladium	7440-05-3	2.83 E-05	1	10000	0.004		43
Subtotal			2.83 E-03	100	1000000	0.43		4256

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	3.89 E-02	100	1000000	5.85		58456

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	4.42 E-03	66.34	663400	0.67		6655
Thermoset	Epoxy resin	Proprietary	3.74 E-04	5.61	56100	0.06		563
Other organic materials	Aliphatic acid anhydride	Proprietary	3.74 E-04	5.61	56100	0.06		563
Other organic materials	2,6 diglycidyl phenyl allyl ether oligome	Proprietary	3.74 E-04	5.61	56100	0.06		563
Other organic materials	Epoxy derivative	Proprietary	3.74 E-04	5.61	56100	0.06		563
Other organic materials	1,4-bis(2,3-epoxypropoxy)butane	Proprietary	3.74 E-04	5.61	56100	0.06		563
Other organic materials	Hexahydromethylphthalic anhydride	Proprietary	3.74 E-04	5.61	56100	0.06		563
Subtotal			6.67 E-03	100.00	1000000	1.00		10031

<b>Package Totals</b>			<b>Weight (g)</b> 6.65 E-01			<b>Percentage (%)</b> 100.00		<b>PPM</b> 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge  
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability  
any inaccuracy of such information.



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